CEL California Eastern Laboratories

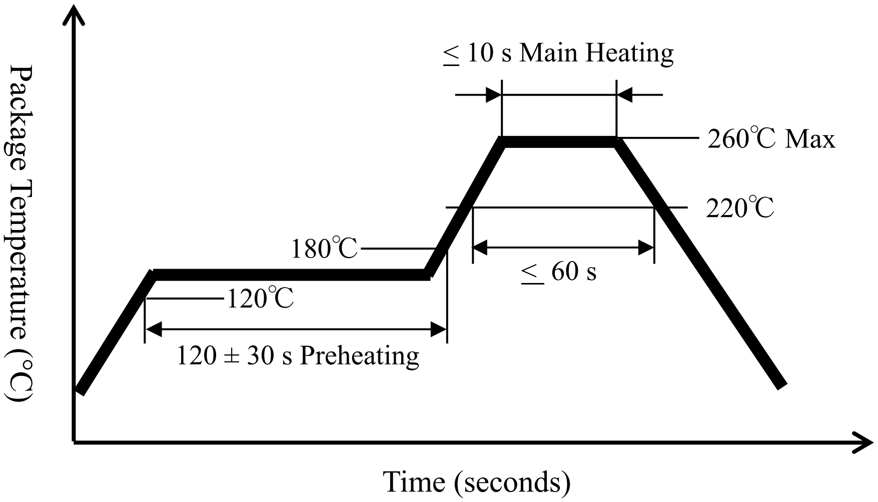
GaAs Switch, FET, LNA IC

Recommended Soldering Conditions for Infrared Reflow

(Hot Air, Infrared + Hot Air Reflow Included)

The following are the recommended soldering conditions for infrared reflow.

- Maximum Temperature (Package's Surface Temperature): 260℃
- Time at Maximum Temperature: 10 seconds or less
- Time at Temperature Higher than 220℃:60 seconds or less
- Preheating Time from 120 to 180℃:120 ± 30 seconds
- Maximum Number of Reflow Processes: 3
- Maximum Chlorine Content of Rosin Flux: 0.2%（wt.）



Infrared Reflow Solder Profile

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